

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD30N03S4L-09	**Issued**	27. April 2022
MA#	MA005734231		
Package	PG-TO252-3-11	**Weight***	369.49 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.783	0.21	0.21	2119	2119
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		175	
	non noble metal	iron	7439-89-6	0.215	0.06		583	
	non noble metal	copper	7440-50-8	215.017	58.18	58.26	581929	582687
wire	non noble metal	aluminium	7429-90-5	1.626	0.44	0.44	4401	4401
encapsulation	inorganic material	zincoxide	1314-13-2	1.277	0.35		3456	
	miscellaneous	miscellaneous	-	6.384	1.73		17278	
	plastics	epoxy resin	-	19.153	5.18		51835	
	inorganic material	silicondioxide	60676-86-0	100.870	27.30	34.56	272999	345568
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10122	10122
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	246	247
solder	non noble metal	tin	7440-31-5	0.021	0.01		58	
	noble metal	silver	7440-22-4	0.027	0.01		72	
	non noble metal	lead	7439-92-1	1.018	0.28	0.30	2756	2886
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.19	5.20	51902	51970
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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